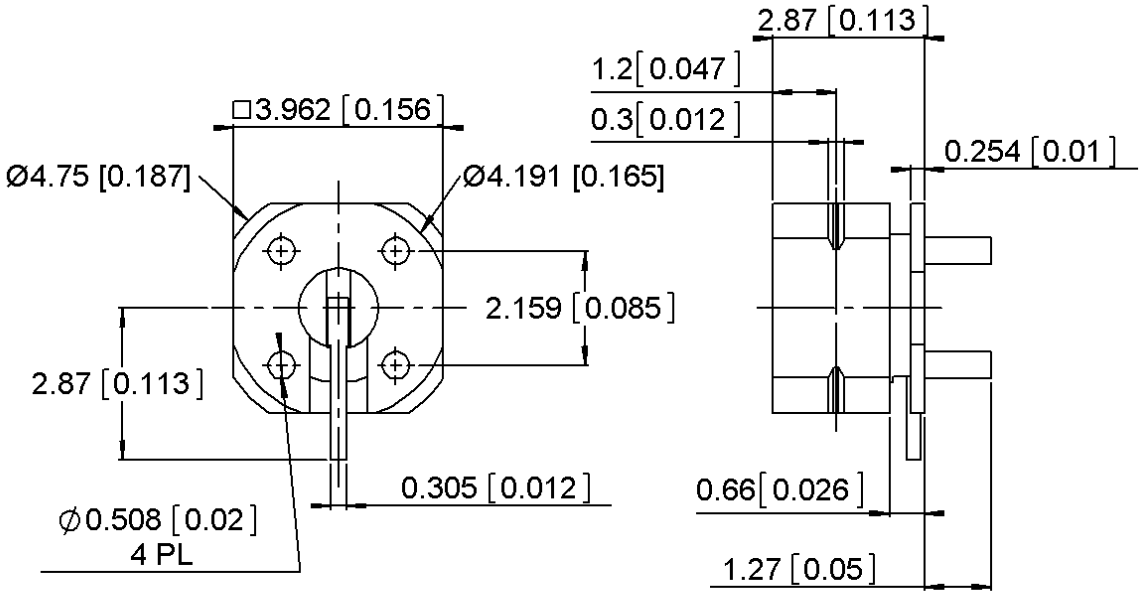
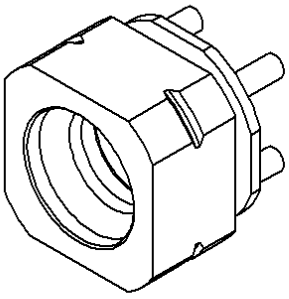
Technical Data Sheet

MALE STRAIGHT RECEPTACLE SMT TYPE - FULL DETENT

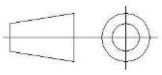
PAGE **1/5**	ISSUE **27-05-15C**	SERIES **SMPM**	PART NUMBER **R201428010**



Scale 1/1



All dimensions are in mm.



COMPONENTS	MATERIALS	PLATING (µm)
Body	**BERYLLIUM COPPER**	**GOLD OVER NICKEL**
Center contact	**BERYLLIUM COPPER**	**GOLD OVER NICKEL**
Outer contact		
Insulator	**PEEK 450G OU PEEK 1000**	
Gasket		
Others parts		
-	-	-
-	-	-

PACKAGING

Standard	Unit	Other
100	**Contact us**	**Contact us**

ELECTRICAL CHARACTERISTICS

Impedance		**50**	Ω
Frequency		**0-20**	GHz
VSWR	* +	**0.0000**	x F(GHz) Maxi
Insertion loss		**0.12**	√F(GHz) dB Maxi
RF leakage	- (	**N/A**	- F(GHz)) dB Maxi
Voltage rating		**335**	Veff Maxi
Dielectric withstanding voltage		**500**	Veff mini
Insulation resistance		**5000**	MΩ mini

MECHANICAL CHARACTERISTICS

Center contact retention		
Axial force – Mating End	**6.7****	N mini
Axial force – Opposite end	**6.7****	N mini
Torque	**NA**	N.cm mini
Recommended torque		
Mating	**NA**	N.cm
Panel nut	**NA**	N.cm
Mating life	**100**	Cycles mini
Weight	**0.0300**	g

ENVIRONMENTAL

Operating temperature	**-65/+165**	°C
Hermetic seal	**NA**	Atm.cm3/s
Panel leakage	**NA**	

SPECIFICATION

OTHER CHARACTERISTICS

Assembly instruction:NA

Others:
***1.15max at 12GHz**
***1.35max at 20GHz**
****after soldering on PCB**

SOLDER PROCEDURE

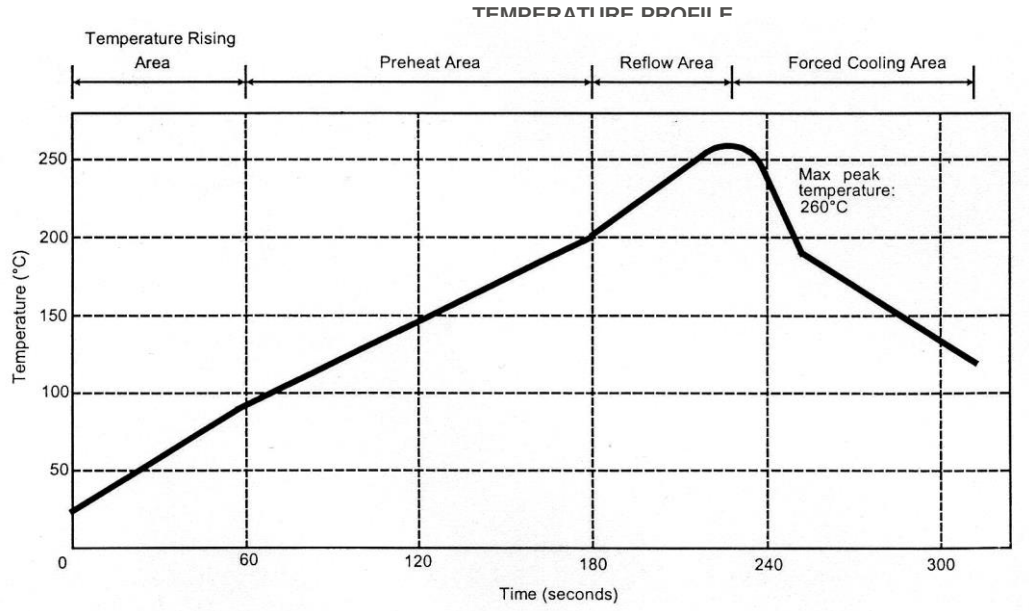
1. Deposition of solder paste 'Sn Ag4 Cu0.5' on mounting zone by screen printing application.
   We recommend a low residue flux.
   We advise a thickness of 150 microns (5.85 microinch). Verify that the edges of the zone are clean.

2. Placement of the receptacle on the mounting zone with an automatic machine of 'pick and place' type.
   Video camera is recommended for the positioning of the component. Adhesive agents must not be used on the receptacle.

3. Soldering by infra-red reflow.
   Below, please find the typical profile to use.

4. Cleaning of printed circuit boards.

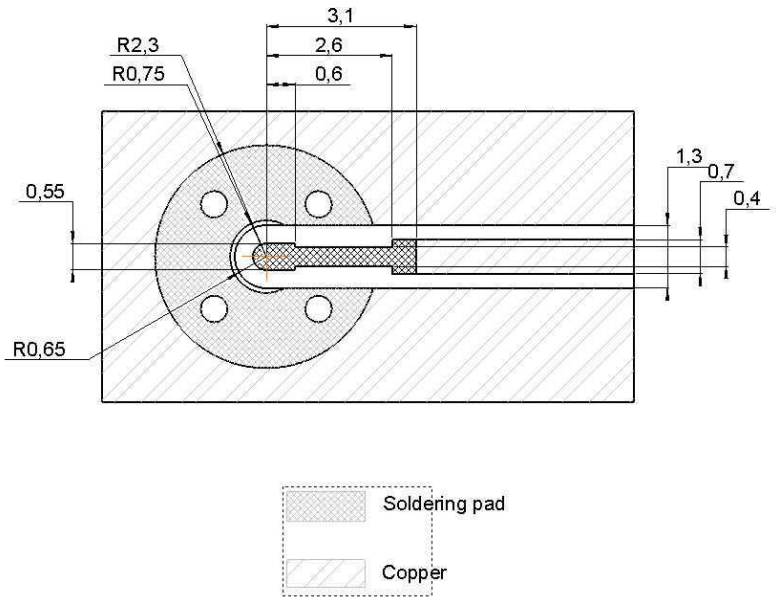
5. Checking of solder joints and position of the component by visual inspection.



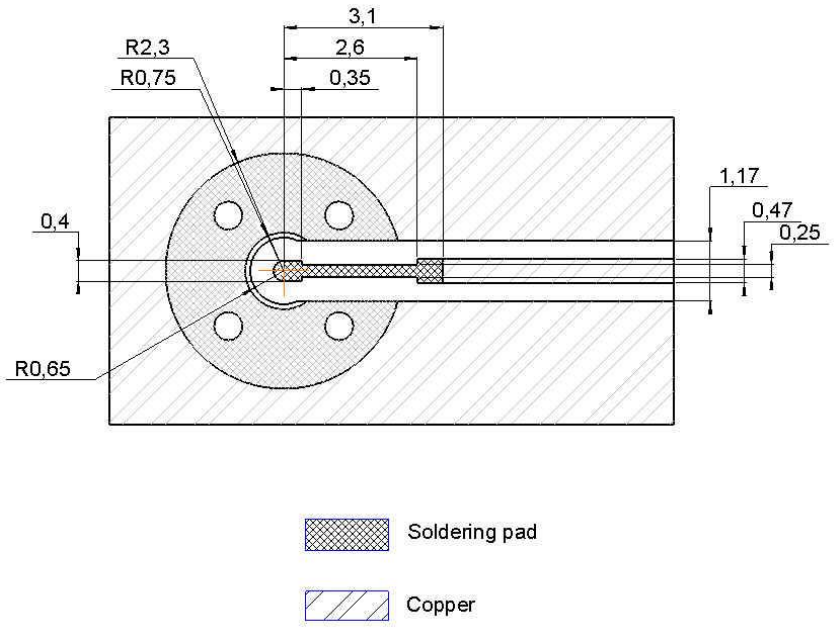
Parameter	Value	Unit
Temperature rising Area	1 - 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to - 4	°C/sec
Max dwell time above 100°C	420	sec

RECOMMENDED PAD DIMENSIONS:

Substrate: RT5880 thickness 0.254mm, with copper layer 35µm on both sides :
Add vias between both sides along upper ground plane according to engineering practise



Substrate: RO4350 thickness 0.254mm, with copper layer 35µm on both sides :
Add vias between both sides along upper ground plane according to engineering practise



Substrate: RO6002 thickness 0.254mm, with copper layer 35µm on both sides :

Add vias between both sides along upper ground plane according to engineering practise